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## **FTDI Chip Launches Sophisticated USB 3.0 Interface Solution in Low Pin Count Package**

11<sup>th</sup> November 2014 – The FT600Q and FT601Q are FTDI Chip's first generation USB 3.0 products that function as SuperSpeed USB 3.0 to FIFO bridges, providing data bursting rates of up to 3.2Gbps. The FT600Q comes in 56-pin QFN package and has a 16-bit wide FIFO bus interface, while FT601Q comes in 76-pin QFN package and has a 32-bit wide FIFO bus interface. Both these chips support up to 8 endpoints, other than the management endpoints. The endpoints are linked to a configurable endpoint buffers of 16kByte length for IN and 16kByte for OUT.

Both FT600Q and FT601Q support two interfacing modes; the 245 FIFO mode and the multi-channel FIFO mode, and thus provide more flexibility for system designers. The 245 FIFO mode has a simpler protocol, but for more sophisticated customers, the multi-channel FIFO mode supports up to 4 logical FIFO channels and data structures optimised for higher throughputs. The FIFO is provided with a 16kByte configurable buffer.

The remote wake up function on these chips can be used to rapidly bring the USB host controller out of suspend mode. The USB battery charger detection function enables USB peripheral devices to detect the presence of a higher current power source in order to boost charging capabilities. It means that the

FT600 can detect connection to a USB-compliant dedicated charging port (DCP) and transmit a signal allowing external logic to switch to charging mode. The IC can also benefit from the higher power delivery capabilities that the USB 3.0 standard supports while still being able to transfer data.

Engineers are furnished with a great deal of flexibility to configure FT600/1Q to their desired application. Among these are multi-function printers, scanners, high resolution video cameras, still image cameras, high definition displays, data acquisition systems, surveillance equipment and medical/industrial imaging systems.

The FT600Q and FT601Q ICs have an operating temperature range that covers -40<sup>0</sup>C to 85<sup>0</sup>C. Catering for a design which incorporates multiple data endpoints, a completely new driver architecture has been developed and optimised to extract full performance from the system whilst maintaining FTDI Chip's standard D2xx API. Driver support provided allows the device to be used with Windows, Linux and Mac operating systems.

For more information on these products visit:

[www.ftdichip.com/Products/ICs/FT600.html](http://www.ftdichip.com/Products/ICs/FT600.html)

### **About FTDI Chip**

FTDI Chip develops innovative silicon solutions that enhance interaction with today's technology. Through application of its "Design Made Easy" ethos, the company is able to support engineers with highly sophisticated, feature-rich, robust and simple-to-use product platforms. These enable creation of electronic designs with higher performance, fewer peripheral components, lower power budgets and diminished board real estate.

FTDI Chip's long-established, continuously expanding Universal Serial Bus (USB) product line boasts such universally recognized product brands as the ubiquitous R-Chip, X-Chip, Vinculum, and H-series. As well as host and bridge chips, it includes highly-integrated system solutions with built-in microcontroller functionality. The company's Embedded Video Engine (EVE) graphic controllers each pack display, audio and touch functionality onto a single chip. The unique, more streamlined approach utilised by these ICs allows dramatic reductions in the development time and bill-of-

materials costs involved in next generation Human Machine Interfaces (HMIs) implementation. FTDI Chip also provides families of highly differentiated, speed-optimised microcontrollers with augmented connectivity features. These application oriented controllers (AOCs) are targeted at key areas where they add value via their elevated processing performance and increased operational efficiency.

FTDI Chip is a fab-less semiconductor company, partnered with the world's leading foundries. The company is headquartered in Glasgow, UK, with research and development facilities located in Glasgow, Singapore and Taipei (Taiwan), plus regional sales and technical support sites in Glasgow, Taipei, Tigard (Oregon, USA) and Shanghai (China).

For more information go to <http://www.ftdichip.com>

**For further information and reader enquiries:**

Susan Glasgow - FTDI Chip

Unit 1, 2 Seaward Place, Centurion Business Park, Glasgow, G41 1HH, UK

Tel: +44 (0) 141 429 2777 Fax: +44 (0) 141 429 2758

E-mail: [marketing@ftdichip.com](mailto:marketing@ftdichip.com)

**Issued by:**

Mike Green - Pinnacle Marketing Communications Ltd

Tel: +44 (0)20 84296543

E-mail: [m.green@pinnaclemarcom.com](mailto:m.green@pinnaclemarcom.com)

Web: [www.pinnacle-marketing.com](http://www.pinnacle-marketing.com)

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